Material Data Declaration Sheet - v003

Version 2.0

Supplier Information

Company Name *	Intel Corporation
Response Document ID	109627
Company Unique ID	047897855
Unique ID Authority	Dun and Bradstreet
Response Date *	2026-04-29

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Supplier Comments

Intel certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Intel completes this form. Intel acknowledges that Customer will rely on this certification in determining the compliance of its products. Customer acknowledges that Intel may have relied on information provided by others in completing this form, and that Intel may not have independently verified such information. However, in situations where Intel has not independently verified information provided by others, Intel agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Customer and the Intel enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Intel's liability and the Customer's remedies for issues that arise regarding information the Intel provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Intel's Standard Terms and Conditions of Sale applicable to such part shall apply.

Product(s)

Product Family Name:

Requester Item Number	Item Number *	Description	Effective Date *	Mass *	UoM*	Comment
	A3CZ135BB23XXXX	Agilex™ 3 FPGA C-Series 135 (B23C)	2026-04-29	1.409	g	

Product Part(s)

ID*	Description	Effective Date*	Units*	% of Product Mass	Comment	
Die	Die	2026-04-29	1	8.792		
Solder Spheres	Solder Spheres	2026-04-29	1	6.938		
Substrate	Substrate	2026-04-29	1	82.141		
Underfill	Underfill	2026-04-29	1	2.129		

Declaration

LHPLA	This product is Low Halogen (Components): Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and PVC in the final product. The replacement of halogenated flame retardants may not be better for the environment. Intel Components as well as purchased components on the finished assembly meet the joint JEDEC/ECA JS-709B requirement.	True
LHPWB	This product is Low Halogen (PCB): Applies Br/Cl in the PCB Laminate. The PCB / Substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants may not be better for the environment	True
REACH-0226	Product(s) is obsolete, no information is available	False
REACH-0226	Product(s) is unknown, no information is available	False
REACH-0226	Product(s) does not contain EU REACH Candidate List substances above the thresholds specified in the REACH Regulation	True
EUROHS-1506	Product(s) does not meet EU RoHS requirements and is not under exemptions	False
EUROHS-1506	Product(s) is obsolete, No Information is Available	False
EUROHS-1506	Product(s) is unknown, no information is available	False
EUROHS-1506	Product(s) Meets EU RoHS Requirements by Application of the Selected Exemption(s)	False
EUROHS-1506	Product(s) Meets EU RoHS Requirements Without Any Exemptions	True

Signature

Intel Product Ecology	C=US, E=productecology@intel.com, OU="", O=Intel Corporation, CN=Intel Product Ecology

Part ID	Description		# of Units	Part Mass %
Die	Die		1	8.792

Homogenous Material Name	Material Class ID	HM Mass UoM	HM Mass Value	Substance Group	Substance Identity	Substance	Substance Mass UoM	Substance Mass Value	Exemption
Die Silicon Material (Generic)		massPercent	99.200			Proprietary Doped Silicon	ppm	1000000.000	
Passivation Layer (143907-02-2)		massPercent	0.800	00193	143907-02-2	Poly(oxy-1,2-ethanediyl), α,α',α'',α'''-(oxydi-3,1,2-	ppm	1700.000	
						Proprietary ingredients	ppm	998300.000	

Part ID	Description		# of Units	Part Mass %
Solder Spheres	Solder Spheres		1	6.938

Homogenous Material Name	Material Class ID	HM Mass UoM	HM Mass Value	Substance Group	Substance Identity	Substance	Substance Mass UoM	Substance Mass Value	Exemption
ECO SOLDER BALL S #7097 0.3mm		mg	97.755		7440-50-8	Copper	ppm	5000.000	
					7440-22-4	Silver	ppm	40000.000	
					7440-31-5	Tin	ppm	955000.000	

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Part ID	Description		# of Units	Part Mass %
Substrate	Substrate		1	82.141

Homogenous Material Name	Material Class ID	HM Mass UoM	HM Mass Value	Substance Group	Substance Identity	Substance	Substance Mass UoM	Substance Mass Value	Exemption
ABF		g	0.126			Epoxy Resin	ppm	360000.000	
					7631-86-9	Silicon Dioxide	ppm	600000.000	
					64742-94-5	Solvent Naphtha (Petroleum), Heavy Aroma	ppm	40000.000	
Copper		g	0.602		7440-50-8	Copper	ppm	1000000.000	
Core		g	0.403			Epoxy Resin	ppm	350000.000	
					65997-17-3	Fibrous-Glass-Wool	ppm	450000.000	
					7631-86-9	Silicon Dioxide	ppm	200000.000	
Gold		g	0.000		7440-57-5	Gold	ppm	1000000.000	
Nickel		g	0.005	00031	7440-02-0	Nickel	ppm	1000000.000	
Palladium		g	0.000		7440-05-3	Palladium	ppm	1000000.000	
Solder mask		g	0.021		7727-43-7	Barium Sulfate	ppm	180000.000	
						Epoxy Resin	ppm	820000.000	

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Part ID	Description		# of Units	Part Mass %
Underfill	Underfill		1	2.129

Homogenous Material Name	Material Class ID	HM Mass UoM	HM Mass Value	Substance Group	Substance Identity	Substance	Substance Mass UoM	Substance Mass Value	Exemption
XS8410-428ND		mg	30.000		25068-38-6	(CHLOROMETHYL)OXIRANE, 4,4'-(1-	ppm	6100.000	
					27610-48-6	6-glycidyloxynapht-1-yl oxymethyloxirane	ppm	35000.000	
						Additives	ppm	8700.000	
						Amine type hardener	ppm	85000.000	
					9003-36-5	FORMALDEHYDE, POLYMER WITH (CHLOROMETHYL)OXIRANE	ppm	190000.000	
					603-35-0	Phosphine, triphenyl-	ppm	1900.000	
					60676-86-0	Silica, Vitreous	ppm	673300.000	